2SA673(A)

Rev.E Mar.-2016

DATA SHEET

/ Descriptions

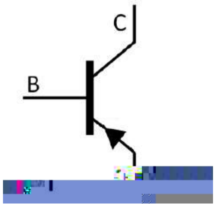
WR0<5 　ṂṂ Ŀ SQS ᴁṀ ҷ s Ⅱ ᄀ 　Silicon PNP transistor in a TO-92 Plastic Package.

љ 5VF4546+D, Й̧ ´

Complementary pair with 2SC1213(A).

ҟ Ḩ ḻ ῶ ᶻ

Low frequency power amplifier.



PIN1 χ Base 　PIN 2 χ Collector 　PIN 3 χ Emitter

/ hFE Classifications & Marking

/ Absolute Maximum Ratings(Ta=25)

v Ὼ Parameter	ɤ ᴺ Symbol		Ὼ Ӫ Rating	ᴅ Ꞙ Unit
Collector to Base Voltage	V_{CBO}	2SA673	-35	V
		2SA673A	-50	
Collector to Emitter Voltage	V_{CEO}	2SA673	-35	V
		2SA673A	-50	
Emitter to Base Voltage	V_{EBO}		-4.0	V
Collector Current - Continuous	I_C		-500	mA
Collector Power Dissipation	P_C		400	mW
Junction Temperature	T_j		150	
Storage Temperature Range	T_{stg}		-55 150	

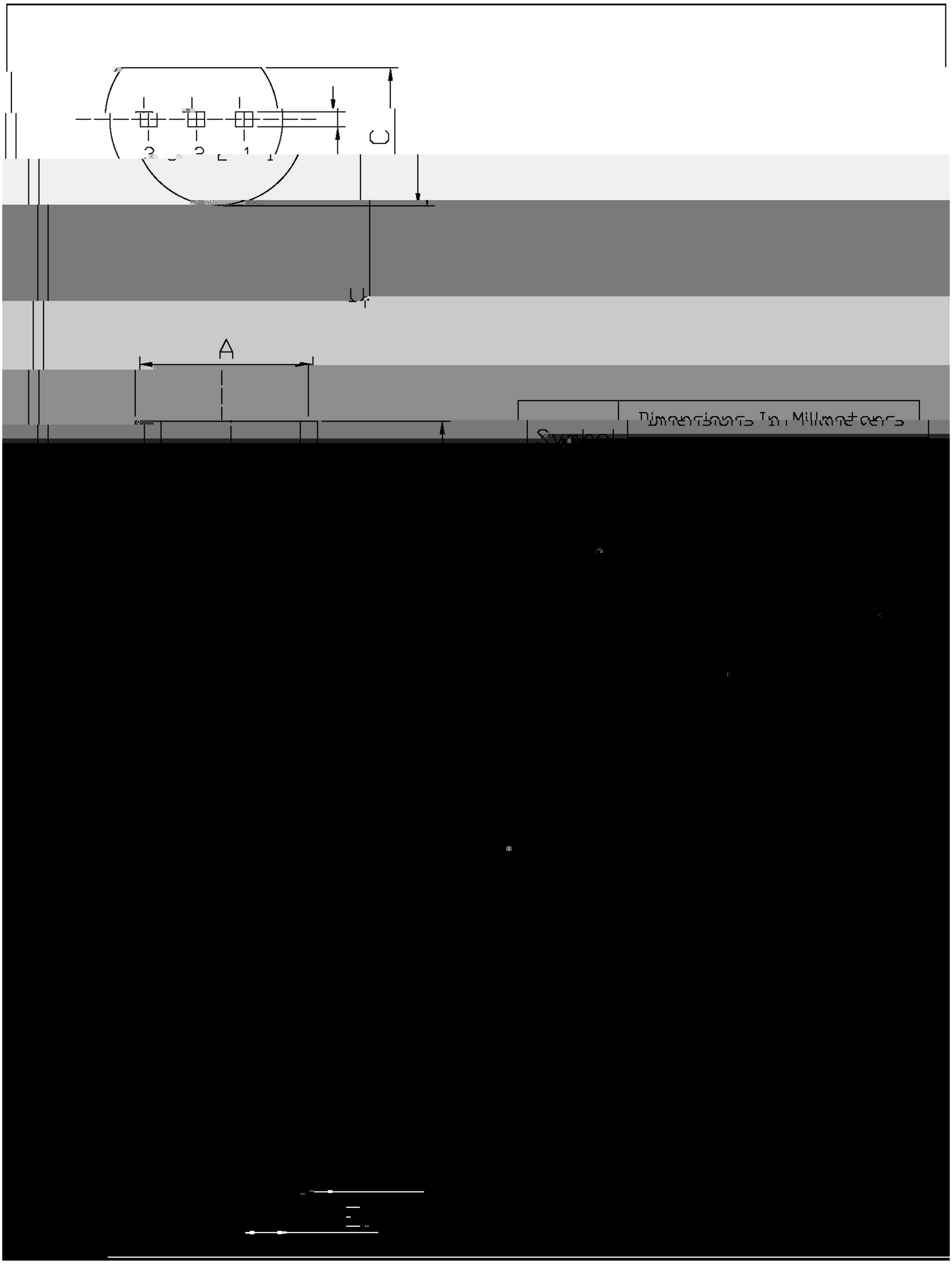
/ Electrical Characteristics(Ta=25)

v Ὼ Parameter	ɤ ᴺ Symbol		╜ ፡ᛏ Ʈ Test Conditions	ῳ ṇ Ӫ Min	Ɛ ʓ Ӫ Typ	ῳ ᶼ Ӫ Max	ᴅ Ꞙ Unit
Collector to Base Breakdown Voltage	V_{CBO}	2SA673	I_C=-10 A I_E=0	-35			V
		2SA673A		-50			
Collector to Emitter Breakdown Voltage	V_{CEO}	2SA673	I_C=-1.0mA I_B=0	-35			V
		2SA673A		-50			
Emitter to Base Breakdown Voltage	V_{EBO}		I_E=-10 A I_C=0	-4.0			V
Collector Cut-Off Current	I_{CBO}		V_{CB}=-20V I_E=0			-0.5	A
DC Current Gain	$h_{FE(1)}$		V_{CE}=-3.0V I_C=-10mA	60		320	
	$h_{FE(2)}$		V_{CE}=-3.0V I_C=-500mA	10			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$		I_C=-150mA I_B=-15mA		-0.2	-0.6	V
Base to Emitter Voltage	V_{BE}		V_{CE}=-3.0V I_C=-10mA		-0.64		V

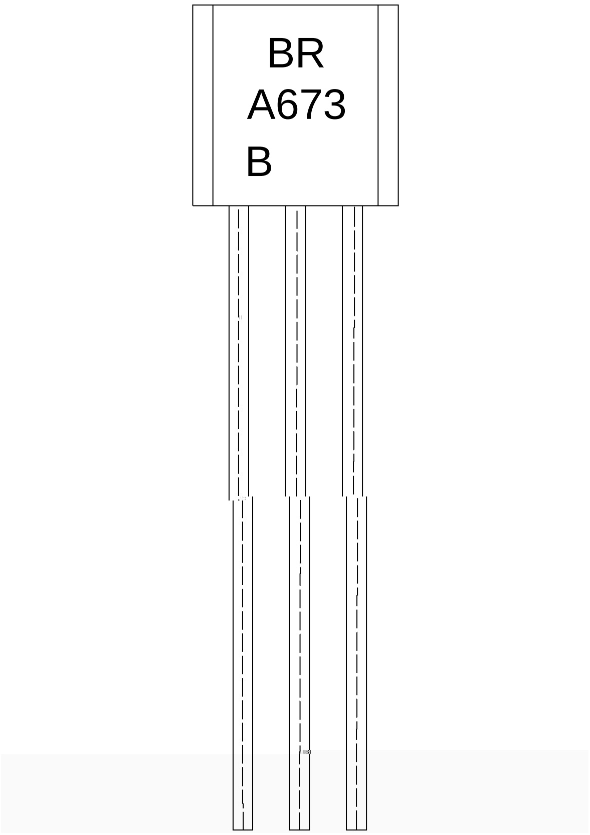
[redacted]

/ Package Dimensions

TO-92 Unit: mm



/ Marking Instructions



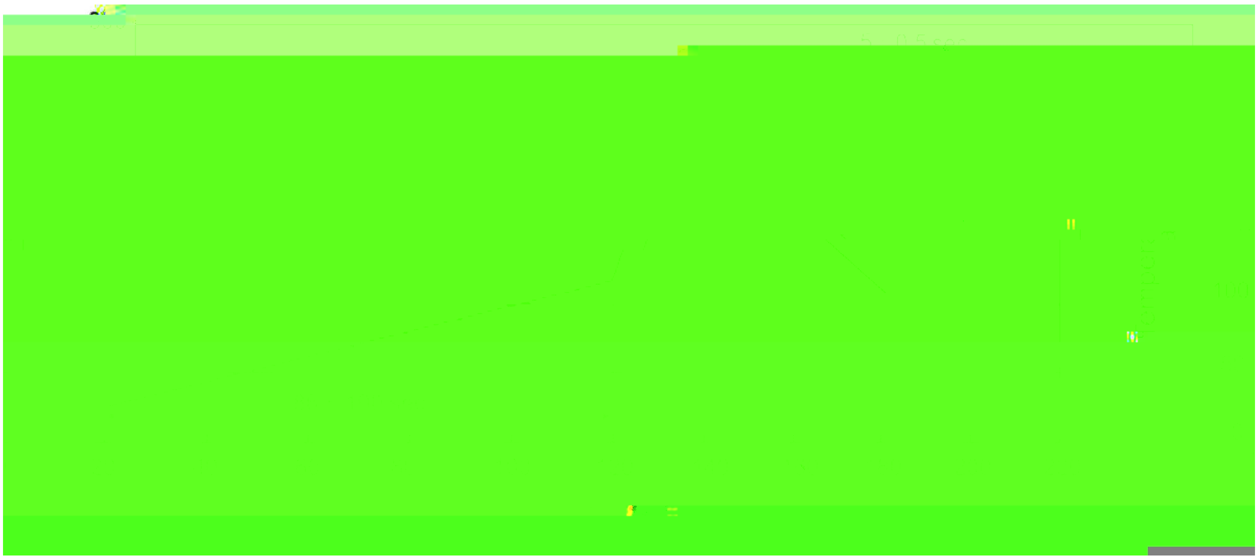
ب ˝ χ

EU꞊	ꞕ ʒ ᴎ Ꞃ
D9 : 6 χ	ꞕ ʒ N Ꞃ
E꞊	ꞕ h_{FE} ˂ 6 Ꞃ
---- χ	ꞕ ꞁ ғ ή N Ꞃ ι ɞ ꞁ ғ ή N ψ ק

Note:

BR:	Company Code.
A673:	Product Type.
B:	h_{FE} Classifications Symbol
****:	Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



ب ˝ χ

1 ɩ ♬ □ ŷ 25 Ḱ 150 ƚ ı `H ڒ 60 Ḱ 90sec;

2 Ś Ӫ □ ŷ 255 ° 5 ƚ ı `H ڒ `Y 𐌽 ㎃ 5 ° 0.5sec;

3 ì ˙ Ⴤ ˛ ɔ ۿ ŷ ㎃ 2 Ḱ 10 ƚ /sec.

Note:

1.Preheating:25~150 ƚ , Time:60~90sec.

2.Peak Temp.:255 ° 5 ƚ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ƚ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ŷ χ 270 ° 5 ƚ `H ڒ χ 10 ° 1 sec.

Temp:270±5 Time:10±1 sec

/ Packaging SPEC.

"Ώ ʈ ɣ ŀ / BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	只袋	袋盒	只盒	盒箱	只箱	袋	盒	箱